

AMENDMENTS TO THE SPECIFICATION

Pages 10 and 11. Please amend the paragraph beginning at line 18 on page 10 and continuing on page 11 as follows:

Also, each ceramics sintered base plate the same as above was completely divided or divided by applying an external force after half cutting by cutting with laser beams or dicing with a cutting blade at a pitch of 5.0 mm the same as above. In this case, each base plate was irradiated with laser beams at a diameter of 120 μm and a pitch of 120 μm . ~~Also, in case of the~~
During half cutting, the time of irradiation with laser beams was controlled such that the ~~depth~~
~~the laser beams reached from 200 to 250 μm in the thickness direction of~~ into the base plate. In addition, with respect to the dicing, a cutting blade having a blade width of 0.2 mm was used and the cutting processing; was carried out while pouring water. In the case of half cutting, the depth was 300 μm .